

UPDATE CHANGE NOTIFICATION

Generic Copy

19-Mar-2009

SUBJECT: ON Semiconductor Update Notification #16235

TITLE: Wafer Fab Transfer for Devices Currently Qualified at ON Semiconductor Piestany, Slovakia Wafer Fab

PROPOSED FIRST SHIP DATE: 20-Jun-2009

AFFECTED CHANGE CATEGORY(S): ON Semi Fab Site / Subcontractor Fab Site

AFFECTED PRODUCT DIVISION(S): Digital Consumer Group

ADDITIONAL RELIABILITY DATA: Contact your local ON Semiconductor Sales Office or Edmond Gallard <edmond.gallard@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is an Update Notification to Initial PCN # 16223, which announced the qualification of TSMC and Gresham wafer fabs as manufacturing sites for devices currently fabricated at the ON Semiconductor Piestany, Slovakia wafer fab. This Update Notification adds 3 part numbers to the list of affected devices (see affected device list at the end of this notification).

ON Semiconductor is pleased to announce that as a result of the previously announced plans to close the Piestany, Slovakia wafer fabrication facility, devices currently qualified for production at that fab are now being qualified for production at ON Semiconductor's Gresham wafer fab (located in Gresham, Oregon) and/or at TSMC wafer fab in Taiwan.

Upon expiration of the associated Final PCN(s), devices may be supplied from any of the qualified fabrication facilities, including the Piestany fab.

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The Gresham wafer fab is compliant to ISO9001:2000, ISO/TS16949:2002, and ISO14001:2004. TSMC is also compliant to ISO9001:2000, ISOTTS16949:2004 and ISO14001:2004. The products are currently manufactured on the Piestany 0.8um PS5LV process. Devices will be qualified to run at Gresham or TSMC on the 0.25 BCD process. Device performance will be the same among the qualified facilities for each device family. All devices will continue to be assembled and tested in existing, qualified locations. No changes to packaging will occur as a result of this foundry expansion qualification.

QUALIFICATION PLAN:

Full qualification testing will be performed as appropriate on each device family. Reliability testing may include the following (depending upon package and device-specific requirements):

<u>Test</u>	<u>Conditions</u>
High Temp Op Life (HTOL)	150C / 504 hrs
High Temp Storage Life (HTSL)	150C / 504 hrs
Pre-Conditioning (PC)	MSL 1 @ 260 ⁰ C
PC + Highly Accelerated Stress Test (PC+HAST)	131C/85%RH/96 hrs/Bias
PC + Unbiased HAST (PC+UHAST)	130C/85%RH/96 hrs/No
bias	
PC + Temp Cycle (PC+TC)	-65C/+150C/500 cyc
ESD	Human Body Model /
	Machine Model
Latch Up	Dynamic Latch Up
PC + SAT	MSL 1 preconditioning @
260°C	
Wire Bond Shear	AEC-Q100-001
Wire Bond Pull	AEC-Mil-Std-883 Meth 2011
Electrical Distribution	On Semi spec

Qualifications at Gresham and/or the TSMC fabs will include a full set of reliability testing for the first devices to be qualified there. When sufficient qualification data has been gathered, future product qualifications will reuse qualification data as appropriate. Electrical distribution data will be collected for each part family at each qualified fab.

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AFFECTED DEVICE LIST:

NCP347MTAETBG

NCP347MTAFTBG

NCP347MTAHTBG

NCP347MTAITBG

NCP348AEMTTBG

NCP348AEMUTBG

NCP348MTTBG

NCP349MNAETBG

NCP360MUTBG

NCP360SNAET1G

NCP360SNAET1GH

NCP360SNAFT1G

NCP360SNAFT1GH

NCP360SNAIT1G

NCP360SNT1G

NCP361MUTBG

NCP361SNT1G

NCP362AMUTBG

NCP362BMUTBG

NCP362CMUTBG

NCP370MUAITXG

NCP372MUAITXG

NCP5021MUTXG

NCP5050MTTXG

NCP5810DMUTXG

NCP5890MUTXG

SUS6160MNTWG *

SUS6160MNTBG * NUS6160MNTWG *

^{* =} Parts added to the Affected Parts list with this Update Notification.